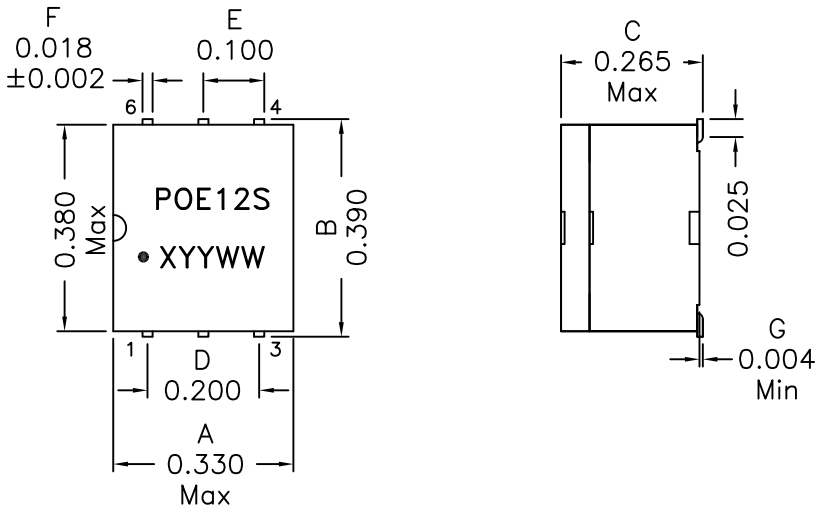
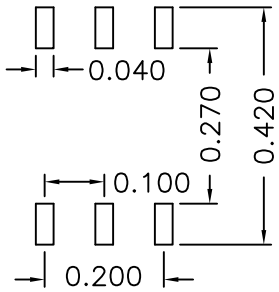
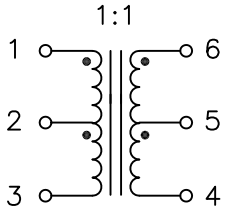
1. Dimensions:





SUGGESTED PCB LAYOUT

2. Schematic:



3. Electrical Specifications: @25°C

OCL: Pins 1−3 350uH Min @100KHz 50mV, 8mAdc

Q: Pins 1−3 8 Min @10KHz 50mV

LL: Pins 1−3 0.25uH Max @1MHz 50mV (short 6−4)

DC Res.: 0.600 Ohms Max, Each Wdg

Cw/w: Pins 1,2,3 to 6,5,4 30pF Max @1MHz 50mV

Turns Ratio: Pins (1−3):(6−4)=1:1±2%

Isolation: 1500Vac, Pri to Sec

DC Line Current: Pin 5 350mA Max @70Vdc Continuous

Notes:

1. Solderability: Leads shall meet MIL−STD−202G, Method 208H for solderability.
2. Flammability: UL94V−0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from −40°C to +85°C
6. Storage Temperature Range: −55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC REV: A/1

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XFMRS Inc www.XFMRS.com	Title: LAN POE XFMR		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XFPOE1−2S		REV. A
	DWN.	Feng	Jan−10−17
	CHK.	YK Liao	Jan−10−17
SHEET 1 OF 1	APP.	BW	Jan−10−17